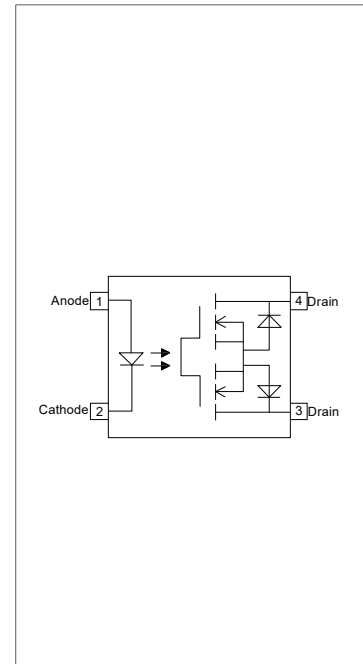


### DESCRIPTION:

The products are 4-pin optical relays. The device is a very small outline non-leaded photorelay suitable for surface-mount assembly. It consists of an infrared LED optically coupled to a photo-MOSFET and is housed in a P-SON4 package. It features a very small on-resistance and fast on/off switching of a high-frequency signal, making it ideal for switching applications in high-speed testers. The products are widely used in automatic test equipment, high-speed logic IC testers, high-speed memory testers and measuring instruments.



### MAIN FEATURES

Isolation voltage 500 Vrms

Operating temperature range -40°C to 110°C

REACH & RoHS compliance

HBM: H3A; MM: M4; CDM: C3

CQC approved

VDE approved

UL approved

### ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	$I_F$	50	mA
	Peak Forward Current	$I_{FP}$	1 <sup>①</sup>	A
	Reverse Voltage	$V_R$	6	V
	Input Power Dissipation	$P_D$	75	mW
Detector	Off-state Output Terminal Voltage	$V_{OFF}$	100	V
	On-state Current	$I_{ON}$	2	A
	On-state Current (pulsed)	$I_{ONP}$	6	A
Isolation Voltage		$V_{iso}$	500 <sup>②</sup>	Vrms
Operating Temperature		$T_{opr}$	-40~110	°C
Junction Temperature		$T_j$	125	°C
Storage Temperature		$T_{stg}$	-55~125	°C

Soldering Temperature	T <sub>sol</sub>	260	°C
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**NOTE1** : 100μs pulse, 100Hz frequency

**NOTE2** : AC for 1minute, R.H.=40~60%

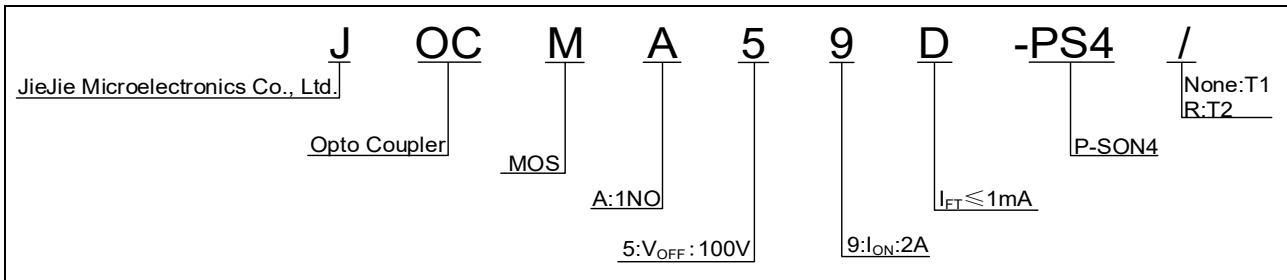
**ELECTRICAL CHARACTERISTICS** (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =10mA	-	1.8	2.5	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> =6V	-	-	1	μA
	Input Capacitance	C <sub>in</sub>	V=0V f=1MHz	-	70	-	pF
Detector	Off-state Current	I <sub>OFF</sub>	V <sub>OFF</sub> =100V	-	-	10	nA
	Output Capacitance	C <sub>OFF</sub>	V=0V f=1MHz t<1s	-	170	-	pF
Coupled	Trigger LED Current	I <sub>FT</sub>	I <sub>ON</sub> =2A	-	0.35	1	mA
	Return LED Current	I <sub>FC</sub>	I <sub>OFF</sub> =10μA	0.1	0.8	-	mA
	On-state Resistance	R <sub>ON</sub>	I <sub>ON</sub> =2A I <sub>F</sub> =5mA t<1s	-	0.5	1	Ω
Switching Characteristics	Isolation Resistance	R <sub>ISO</sub>	DC500V 40~60%R.H.	-	10 <sup>14</sup>	-	Ω
	Turn On Time	t <sub>on</sub>	I <sub>F</sub> =5mA	-	1.1	3	ms
	Turn Off Time	t <sub>off</sub>	I <sub>L</sub> =Max.	-	0.05	1	ms

**Recommended Operating Conditions**

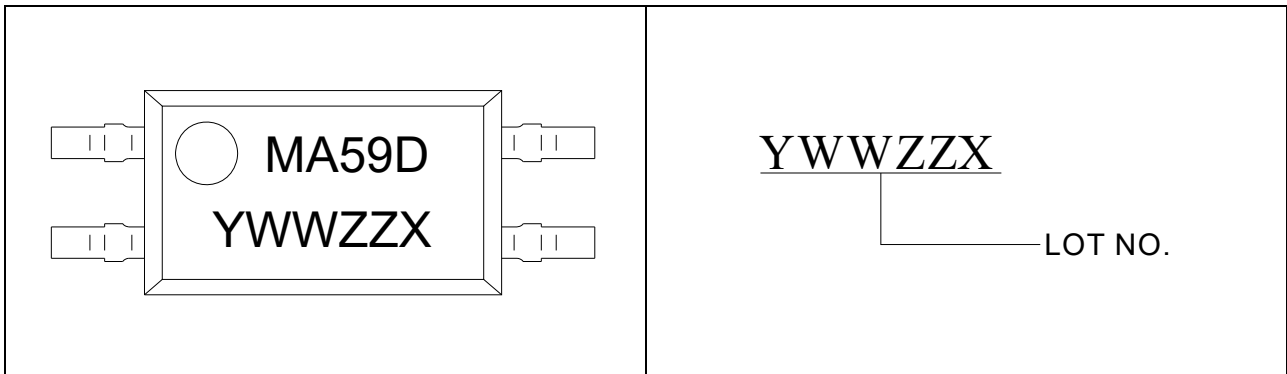
Characteristics	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	V <sub>DD</sub>	-	-	80	V
Input Forward Current	I <sub>F</sub>	-	5	20	mA
On-state Current	I <sub>ON</sub>	-	-	2	A
Operating Temperature	T <sub>opr</sub>	-40	-	110	°C

**ORDERING INFORMATION**



Packing Quantity	
Option	Quantity
None/R	1500 Units/Reel

**MARKING**



Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

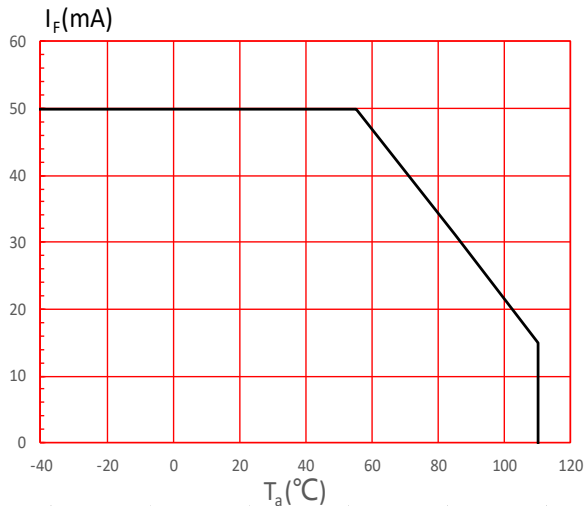


FIG.2: On-state Current vs. Ambient Temperature

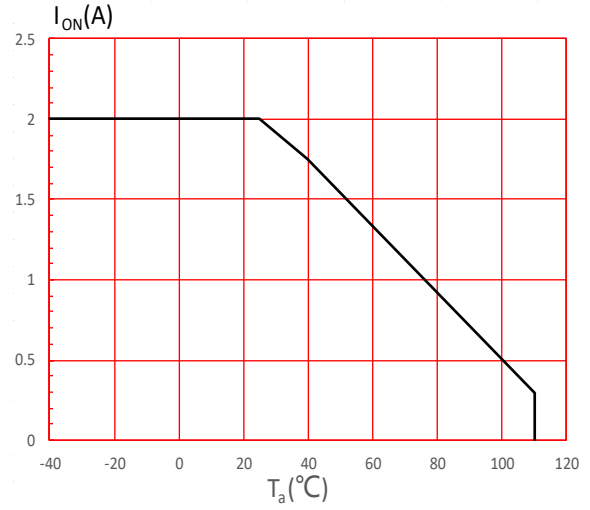


FIG.3: LED Forward Current vs. LED Dropout Voltage

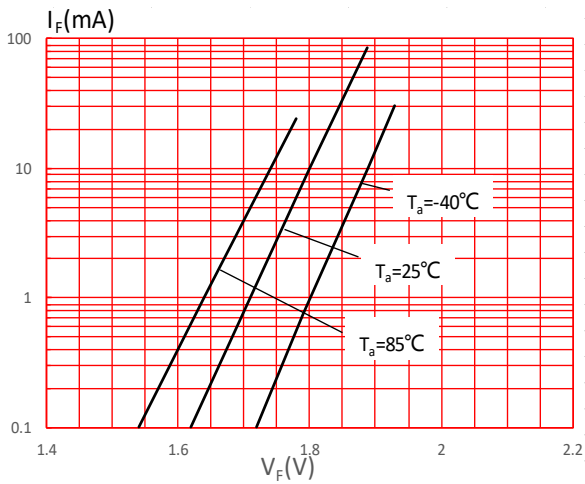


FIG.4: On-state Current vs. On-state Voltage

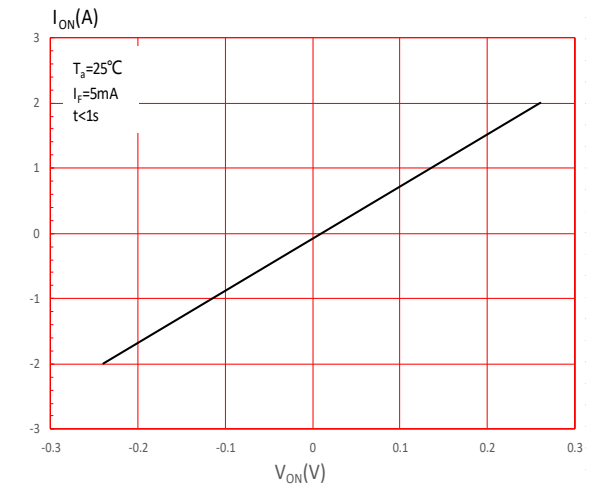


FIG.5: On Resistance vs. Ambient Temperature

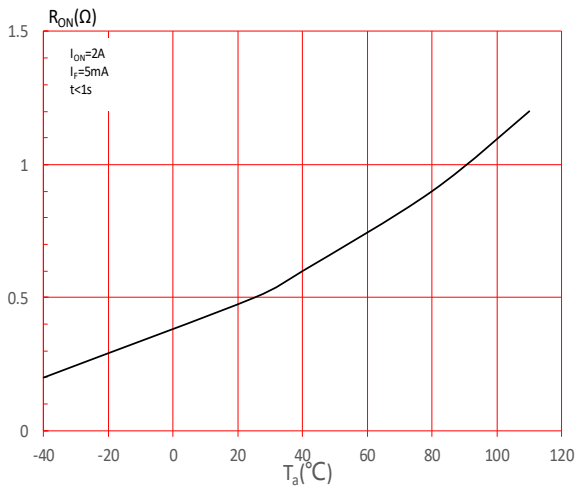


FIG.6: Trigger LED Current vs. Ambient Temperature

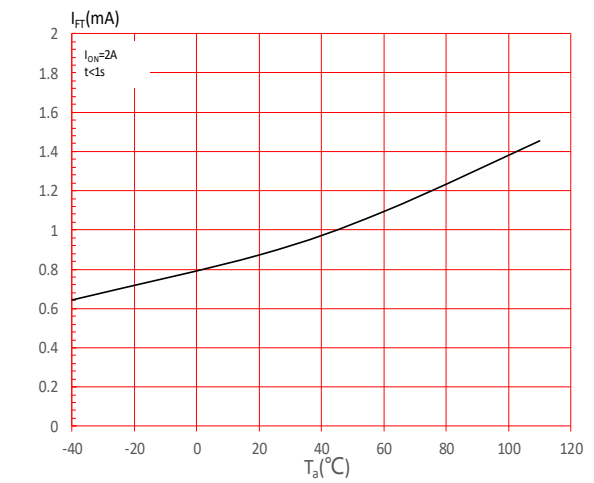


FIG.7: T<sub>ON</sub>, T<sub>OFF</sub> vs. LED Forward Current

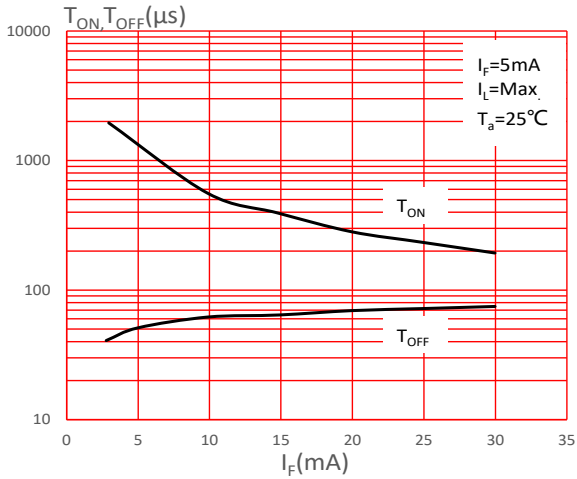


FIG.8: T<sub>ON</sub>, T<sub>OFF</sub> vs. Ambient Temperature

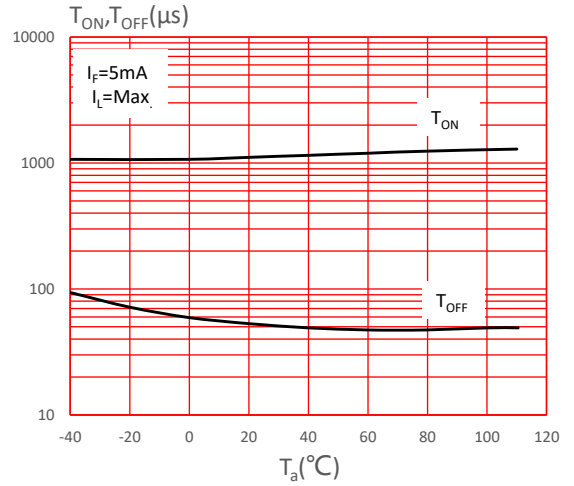


FIG.9: Off-state Current vs. Off-state Voltage

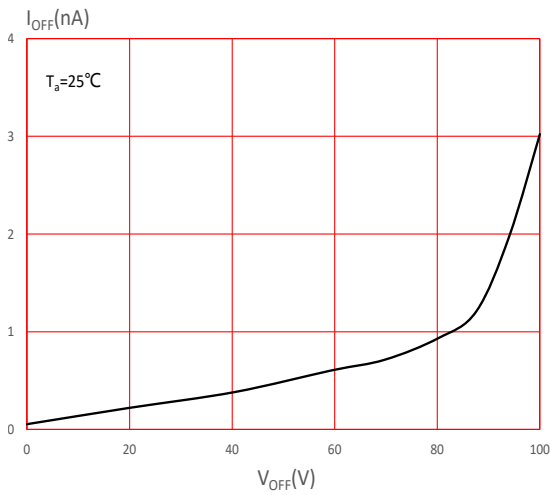


FIG.10: Off-state Current vs. Ambient Temperature

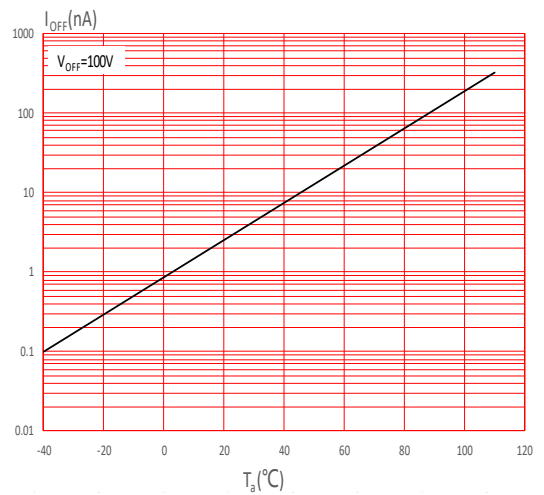
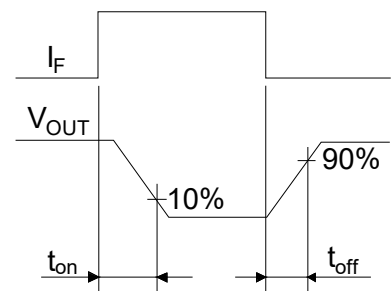
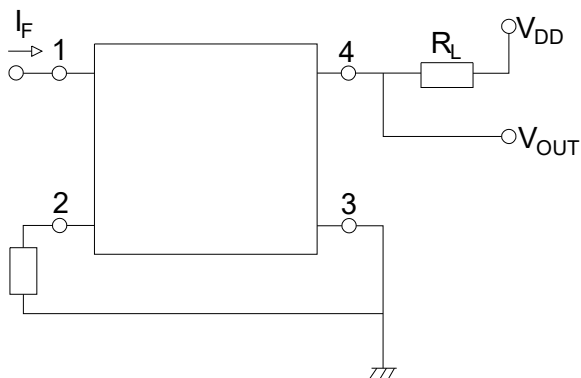
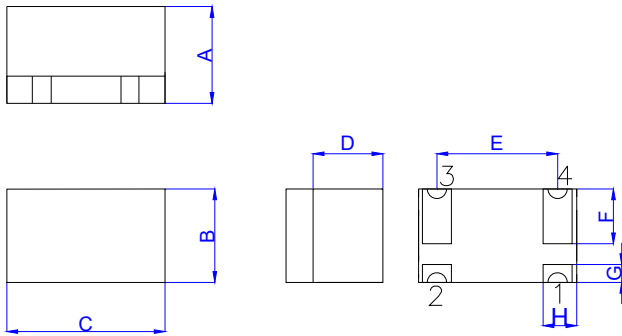


Fig.11: Switching Time Test Circuit and Waveform

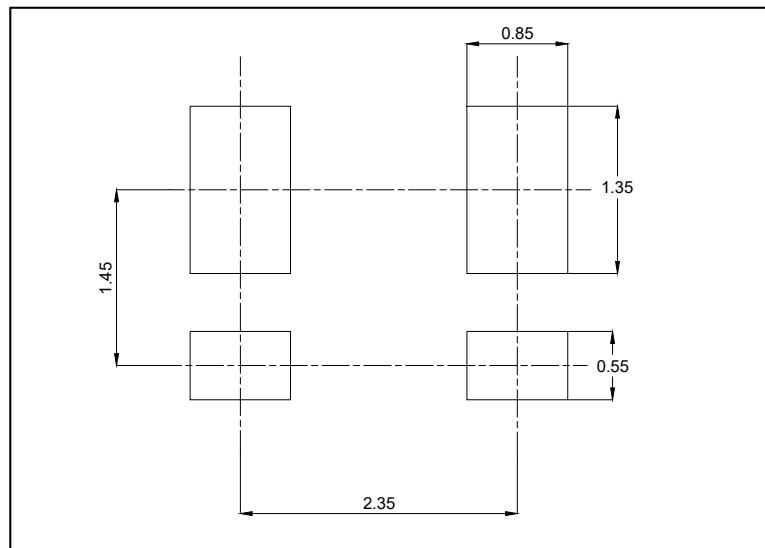


Package Dimension (Unit: mm)

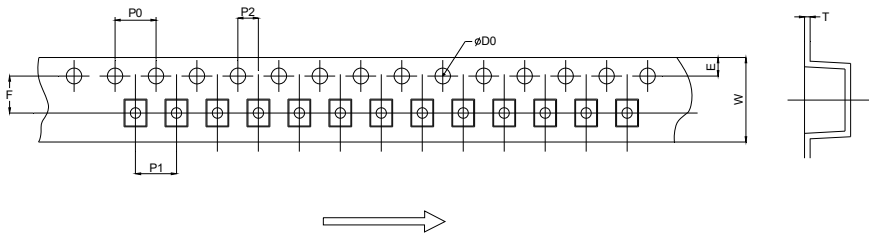


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.30		1.70	0.051		0.067
B	1.90		2.30	0.075		0.091
C	3.20		3.60	0.126		0.142
D	0.88		1.28	0.035		0.050
E	2.15		2.55	0.085		0.100
F	1.00		1.40	0.039		0.055
G	0.20		0.60	0.008		0.024
H	0.65		1.05	0.026		0.041

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

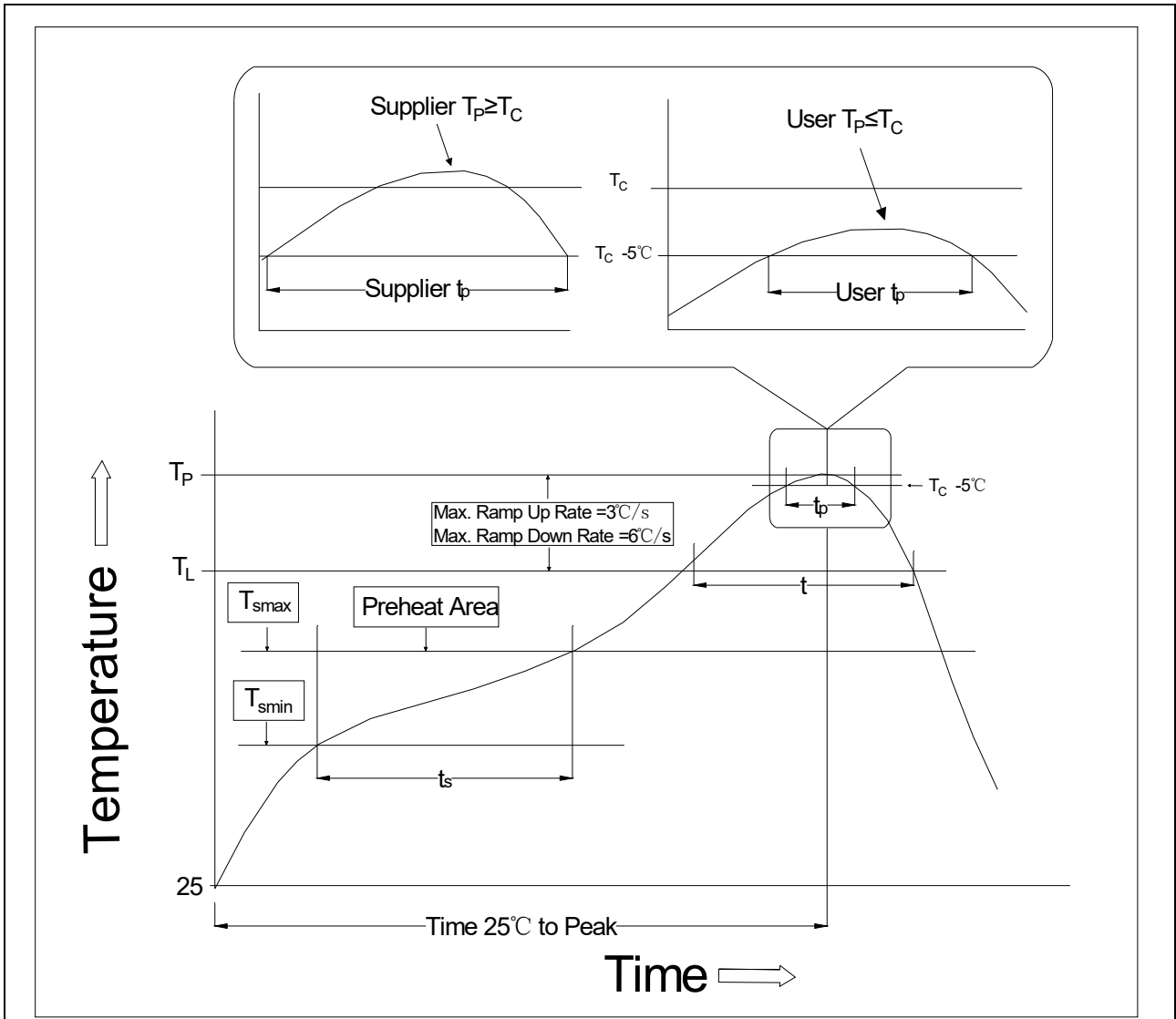


**CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	3.90	4.00	4.10	0.154	0.157	0.161
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	3.40	3.50	3.60	0.134	0.138	0.142
T	0.20	0.25	0.30	0.008	0.010	0.012
W	7.70	8.00	8.30	0.303	0.315	0.327

REFLOW INFORMATION




Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	100	150°C
Temperature Max. (T <sub>smax</sub> )	150	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.	3°C/second max.
Liquidus Temperature (T <sub>L</sub> )	183°C	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 3

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